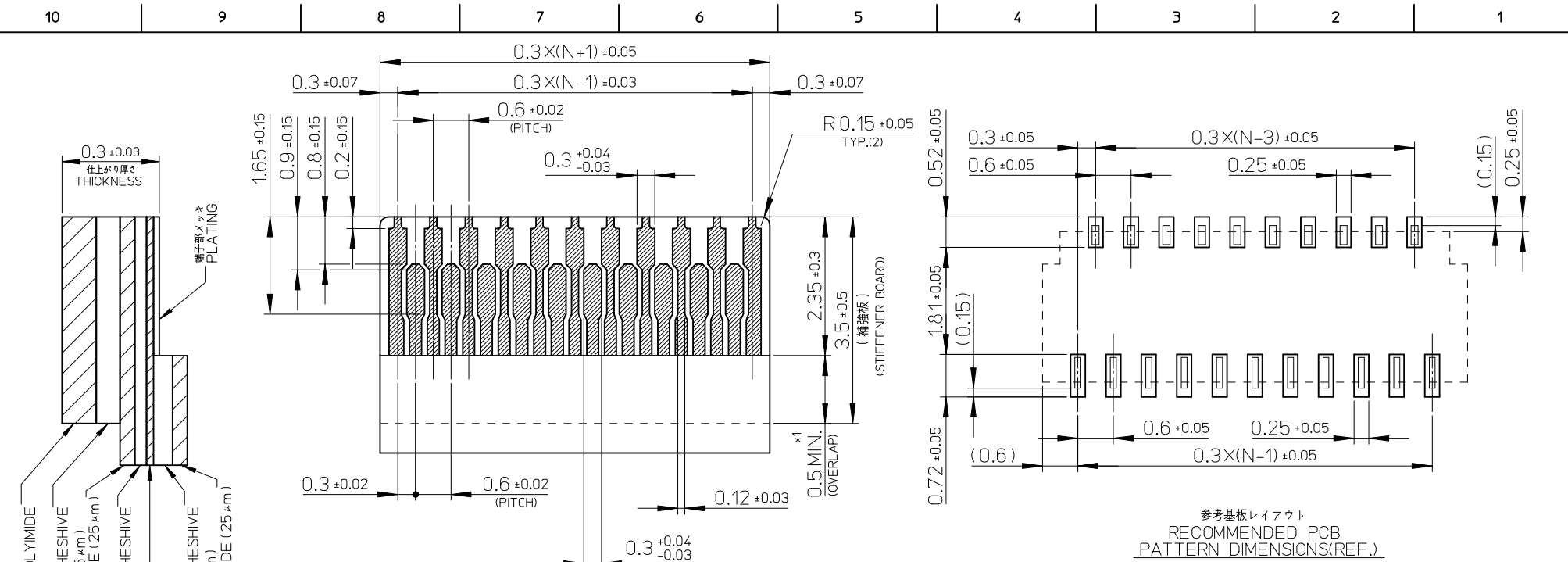


注記 NOTES

- 使用材料 MATERIAL  
 ハウジング: 液晶ポリマー(LCP)、ナチュラル(白色系)、ガラス充填、UL94V-0  
 奇数端子: 燐青銅、ニッケル下地、金メッキ  
 偶数端子: 燐青銅、ニッケル下地、金メッキ  
 HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL(WHITE)  
 GLASS FILEED, UL94V-0  
 ODD TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING  
 EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部: 金メッキ 0.1μm以上  
 テール部: 金メッキ  
 下地: ニッケルメッキ 1.0μm以上  
 CONTACT AREA: GOLD PLATING 0.1μm MINIMUM  
 TAIL AREA: GOLD PLATING  
 UNDER PLATING: NICKEL PLATING 1.0μm MINIMUM
- 端子のコプラナリティーは 0.1 以下とする。  
 COPLANALITY OF SOLDER TAILS: 0.1MAX.
- ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT
- 一般公差: ±0.3  
 GENERAL TOLERANCE: ±0.3

6.0	4.8	5.4	6.6	504281-1900	19
5.4	4.2	4.8	6.0	504281-1700	17
4.2	3.0	3.6	4.8	504281-1300	13
3.6	2.4	3.0	4.2	504281-1100	11
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUIT

RELEASED EC NO.: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07 REV: O	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER ±0.2		DRAWN BY NNISHI		DATE 2012/07/17		TITLE 0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM		
	10 OVER 30 UNDER ±0.25		CHECKED BY HIJIMA		DATE 2012/07/17				
	30 OVER ±0.3		APPROVED BY YNOGAWA		DATE 2014/05/07				
	ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-504281-001		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



補強板: ポリイミド  
 STIFFENER BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム: ポリイミド (25µm)  
 BASE FILM: POLYIMIDE (25µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 導体部: 銅箔 (35µm)  
 COPPER FOL (35µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバーレイ: ポリイミド (25µm)  
 COVER FILM: POLYIMIDE (25µm)

FPC 構成推奨仕様  
 STRUCTURE OF FPC

適合するFPC推奨寸法 (参考)  
 APPLICABLE FPC  
 PATTERN DIMENSIONS(REF.)  
 (端子仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)

参考基板レイアウト  
 RECOMMENDED PCB  
 PATTERN DIMENSIONS(REF.)

推奨ペースト厚: 100µm  
 推奨マスク開口率: 80%  
 RECOMMEND SCREEN THICKNESS: 100µm  
 RECOMMEND SCREEN OPEN RATIO: 80%

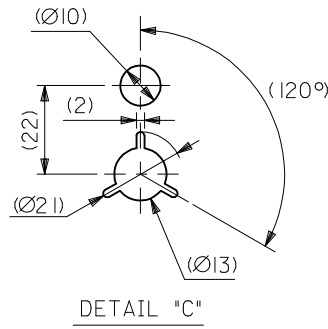
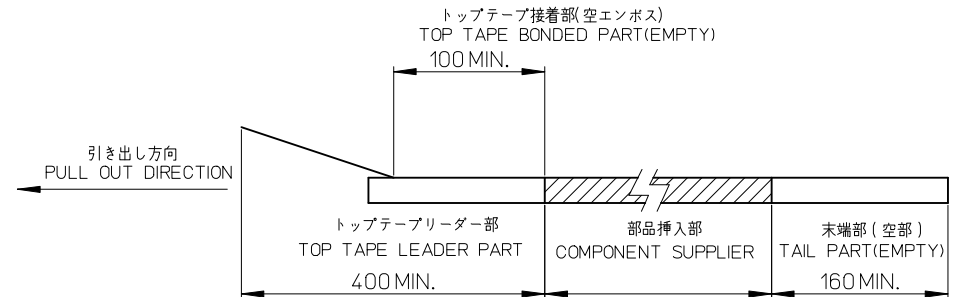
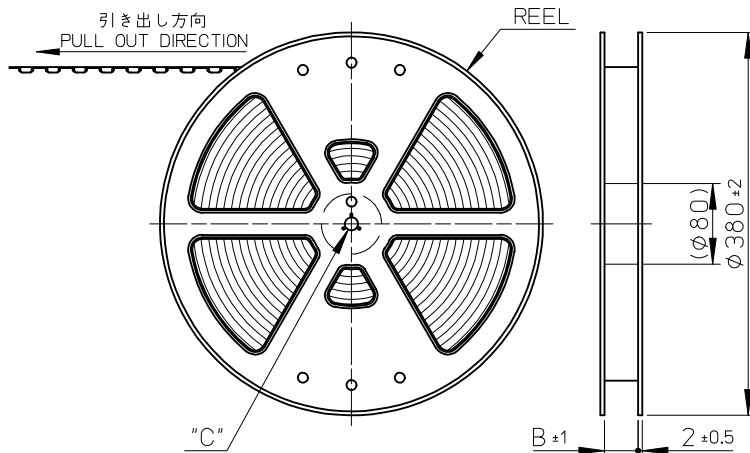
・FPCについて (ABOUT FPC)  
 抜き方向は、導体側から補強板側を推奨します。  
 補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は同通不良の原因となりますので、  
 染み出しが無い様お願いします。  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE  
 RECOMMENDED MATERIAL:  
 STIFFENER BOARD: POLYIMIDE  
 BONDING AGENT: THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様 (FPC PATTERN PLATING)  
 金メッキ: 0.1µm以上  
 下地ニッケルメッキ: 2~6µm  
 GOLD PLATING: 0.1µm MINIMUM  
 NICKEL UNDER PLATING: 2~6µm  
 \*1 補強板長さが図面通り確保できない場合は、カバーレイと  
 補強板のオーバーラップ寸法を0.5mm以上として下さい。  
 WHEN STIFFENER BOARD DIMENSION CAN NOT  
 SECURE AS DRAWING, PLEASE GIVE THE OVERLAP  
 SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	15:1	METRIC		
	10 UNDER	+0.2	DRAWN BY	DATE	TITLE		
	10 OVER	±0.25	HIJIMA	2012/07/17	0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM		
30 OVER	±0.3	YNOGAWA	2014/05/07	molex			
0	ANGULAR ±1 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1		SD-504281-001		2 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

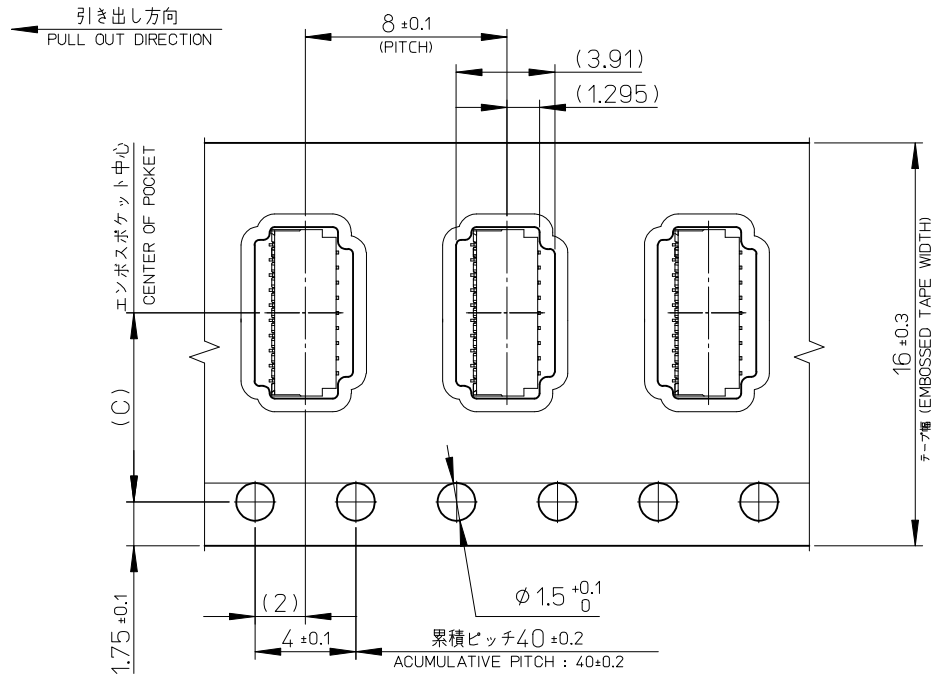
- 製品詳細寸法については図面SD-504281-001を参照下さい。  
CONNECTOR DETAILED DIMENSIONS, REFER TO SD-504281-001.
- 梱包数量: 5000個/リール  
NUMBER OF CONNECTORS : 5000PCS / REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)  
トップテープ(TOP TAPE) : PET, PE, PEF  
リール(REEL) : ポリスチレン(POLYSTYRENE) <リサイクル材を含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剥離強度については、IEC60286-3に準拠  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3

RELEASED EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE				
	10 OVER 30 UNDER	± 0.25	SKUROSE	2013/05/20	0.3 FPC CONN NON-ZIF TYPE HGT=1.0MM <b>molex</b>				
	30 OVER	± 0.3	HIJIMA	2013/05/20					
ANGULAR	± 1 °	APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		YNOGAWA 2014/05/07		SEE CHART		SD-504281-002		1 OF 2	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1



7.5	17.4	6.6	504281-1900	19
		6.0	504281-1700	17
		4.8	504281-1300	13
		4.2	504281-1100	11
C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	種 教 CkT.

SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN:SKUROSE 2014/04/28 CHKD:H I J I M A 2014/04/28 APPR:YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE			
	10 OVER 30 UNDER	±0.25	SKUROSE	2013/05/20	0.3 FPC CONN NON-ZIF TYPE HGT=1.0MM			
	30 OVER	±0.3	CHECKED BY	DATE				
	ANGULAR	±1 °	H I J I M A	2013/05/20	molex			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE					
O	REV	YNOGAWA	2014/05/07	MATERIAL NO.	DOCUMENT NO.	SEE SHEET 1		SD-504281-002
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SHEET NO. 2 OF 2

9 8 7 6 5 4 3 2